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TRANSMITTAL FORM

(to be used for all correspondence after initial filing)

Total Number of Pages in This Submission **8**

Application Number	10/772,204 (Patent No. 6,917,107 B2)
Filing Date	February 3, 2004 (Issued July 12, 2005)
First Named Inventor	Salman Akram
Art Unit	2826
Examiner Name	Fetsum Abraham
Attorney Docket Number	MI22-2499

ENCLOSURES (Check all that apply)

<input type="checkbox"/> Fee Transmittal Form <input type="checkbox"/> Fee Attached <input type="checkbox"/> Amendment/Reply <input type="checkbox"/> After Final <input type="checkbox"/> Affidavits/declaration(s) <input type="checkbox"/> Extension of Time Request <input type="checkbox"/> Express Abandonment Request <input type="checkbox"/> Information Disclosure Statement <input type="checkbox"/> Certified Copy of Priority Document(s) <input type="checkbox"/> Reply to Missing Parts/ Incomplete Application <input type="checkbox"/> Reply to Missing Parts under 37 CFR 1.52 or 1.53	<input type="checkbox"/> Drawing(s) <input type="checkbox"/> Licensing-related Papers <input type="checkbox"/> Petition <input type="checkbox"/> Petition to Convert to a Provisional Application <input type="checkbox"/> Power of Attorney, Revocation Change of Correspondence Address <input type="checkbox"/> Terminal Disclaimer <input type="checkbox"/> Request for Refund <input type="checkbox"/> CD, Number of CD(s) _____ <input type="checkbox"/> Landscape Table on CD	<input type="checkbox"/> After Allowance Communication to TC <input type="checkbox"/> Appeal Communication to Board of Appeals and Interferences <input type="checkbox"/> Appeal Communication to TC (Appeal Notice, Brief, Reply Brief) <input type="checkbox"/> Proprietary Information <input type="checkbox"/> Status Letter <input checked="" type="checkbox"/> Other Enclosure(s) (please identify below): PTO Return Receipt Postcard Request for Certificate of Correction-PTO Mistakes Certificate of Correction-in duplicate
<div>Remarks</div> <div>Customer No. 021567</div> <div>NO FEE IS REQUIRED WITH THIS FILING.</div> <div>However should a fee be determined as owing, please charge such fee to Deposit Account No. 23-0925</div>		

Certificate
JUN 27 2006
of Correction

SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

Firm Name	Wells St. John P.S.		
Signature	<i>[Handwritten Signature]</i>		
Printed name	David G. Latwesen, Ph.D.		
Date	6/20/06	Reg. No.	38,533

CERTIFICATE OF TRANSMISSION/MAILING

I hereby certify that this correspondence is being facsimile transmitted to the USPTO or deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date shown below:

Signature	<i>Muriel G. Dunnigan</i>		
Typed or printed name	Muriel G. Dunnigan	Date	June 20, 2006

This collection of information is required by 37 CFR 1.5. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to 2 hours to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.

JUN 28 2006



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent No.6,917,107 B2
Patent Issue Date July 12, 2005
Application Serial No. 10/772,204
Filing Date February 3, 2004
Assignee Micron Technology, Inc.
Inventorship Salman Akram
Attorney's Docket No. MI22-2499
Title: A Board-On-Chip Package Having A Chip Provided with Flexible Conductor
on the Surface

REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT
FOR PTO MISTAKE (37 C.F.R. 1.322(a))

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
ATTN: Decision and Certificate of Correction
Branch of the Patent Issue Division

From: David G. Latwesen, Ph.D.
Wells St. John P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3828
(Tel. 509-624-4276; Fax 509-838-3424)

Sir:

It is hereby requested that a Certificate of Correction be issued with respect to Patent No. 6,917,107 B2, granted July 12, 2005, in accordance with the Certificate of Correction form attached hereto in duplicate.

The errors listed on the Certificate of Correction form were apparently incurred through the fault of the PTO as will be disclosed by the records of files in the Office.

Since this Certificate of Correction is being requested due to PTO errors, it is believed that no fee is due. However, in the event that a fee is required for

JUN 28 2006

issuance of this Certificate of Correction, please charge the fee specified under 37 C.F.R. § 1.20(a) to Deposit Account No. 23-0925. Please credit Deposit Account No. 23-0925 with any overpayment of the above fee.


Attached hereto, in duplicate is Form PTO-1050, with at least one copy being suitable for printing.

Respectfully submitted,

Dated: _____



By: _____


David G. Latwesen, Ph.D.
Reg. No. 38,533

JUN 28 2006

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : US 6,917,107 B2
ISSUED : July 12, 2005
APPLICATION NO.: 10/772,204
FILED : February 3, 2004
INVENTOR : Salman Akram

It is certified that errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Col. 4, line 30 –

Replace "conductive material **80** can it improve dissipation of heat"
With --conductive material **80** can improve dissipation of heat--

Col. 4, line 44 –

Replace ".**80** contacts substrate **52** at a first location **82** proximate first"
With --**80** contacts substrate **52** at a first location **82** proximate first--

Col. 5, line 10 –

Replace "second surface **66** of **5** die **62**, with die **62** being illustrated"
With --second surface **66** of die **62**, with die **62** being illustrated--

Col. 7, line 11 –

Replace "Thermally conductive a material **80e** can this comprise"
With --Thermally conductive material **80e** can this comprise--

Col. 7, line 41 –

Replace "plurality of chips **62f** formed if over substrate **52f**. Substrate"
With --plurality of chips **62f** formed over substrate **52f**. Substrate--

Page
1 of 2

Mailing Address of Sender:

David G. Latwesen, Ph.D.
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Patent No. US 6,917,107 B2

JUN 28 2008

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : US 6,917,107 B2
ISSUED : July 12, 2005
APPLICATION NO.: 10/772,204
FILED : February 3, 2004
INVENTOR : Salman Akram

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Col. 7, line 44 –

Replace “A plurality-of slits 54f extend through substrate 52f.”

With --A plurality of slits 54f extend through substrate 52f.--

Col. 7, line 50 –

Replace “connected is with the circuitry on surface 56f with electrical”

With --connected with the circuitry on surface 56f with electrical--

Col. 8, line 34 –

Replace “to locations wherein thermally 13 conductive”

With --to locations wherein thermally conductive--

Col. 9, line 14 –

Replace “is wrapped 12 around chip 62g. In the shown embodiment”

With --is wrapped around chip 62g. In the shown embodiment--

Col. 9, line 46 –

Replace “of 18 chip 62g.”

With --of chip 62g.--

Page
2 of 2

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Patent No. US 6,917,107 B2

JUN 28 2008

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

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